

20V P-Channel Enhancement Mode MOSFET

<p>Description</p> <p>The CP55P02D6 uses advanced trench technology to provide excellent $R_{DS(ON)}$. This device is suitable for use as a load switch or in PWM applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ◆ $V_{DS} = -20V$ $I_D = -55A$ $R_{DS(ON)}(Typ.) = 6m\Omega$ @ $V_{GS} = -4.5V$ $R_{DS(ON)}(Typ.) = 7.5m\Omega$ @ $V_{GS} = -2.5V$ ◆ High power and current handling capability ◆ Lead free product is acquired ◆ Surface mount package ◆ 150 °C operating temperature ◆ 100% UIS tested <p>Application</p> <ul style="list-style-type: none"> ◆ PWM applications ◆ Load switch ◆ Uninterruptible power supply <p>Package</p> <ul style="list-style-type: none"> ◆ PDFN5*6-8L-A 	<p>Schematic diagram</p> <p>Marking and pin assignment</p> <p>PDFN5 × 6-8L</p> <div style="display: flex; justify-content: space-around;"> <div style="text-align: center;"> <p>Top View</p> </div> <div style="text-align: center;"> <p>Bottom View</p> </div> </div> <p>XXXX—Wafer Information YYYY—Quality Code</p>
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Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
CP55P02D6-G	-55°C to +150°C	PDFN5*6-8L-A	5000

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	V_{DS}	-20	V
Gate-source voltage	V_{GS}	±12	V
Continuous Drain Current	I_D	TC=25°C	-55
		TC=70°C	-49
Pulsed Drain Current	I_{DM}	-220	A
Avalanche energy ($T_J = 25^\circ C$, $V_{DD} = 20V$, $V_G = 10V$, $L = 0.5mH$, $R_g = 25\Omega$)		E_{AS}	130
Power Dissipation	P_D	TC=25°C	100
		TC=70°C	65
Operating junction Temperature range		T_J	-55—150

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-20	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-20V, V _{GS} =0V	-	-	1	μA
		T _J =85°C	-	-	30	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-0.5	-0.7	-1.0	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =-4.5V, I _D =-20A	-	6	7.5	mΩ
		V _{GS} =-2.5V, I _D =-10A	-	7.5	9	
On Status Drain Current	I _{D(ON)}	V _{DS} =-10V, V _{GS} =-2.5V	-	55	-	A
Diode Characteristics						
Diode Forward Voltage ¹	V _{SD}	I _{SD} =-20A, V _{GS} =0V	-	-0.8	-1.3	V
Diode Continuous Forward Current	I _S		-	-55	-	A
Reverse Recovery Time	t _{rr}	I _F =-20A,	-	24	-	ns
Reverse Recovery Charge	Q _{rr}	dI/dt=-100A/us	-	16	-	nC
Dynamic Characteristics²						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	6.2	-	Ω
Input capacitance	C _{ISS}	V _{GS} =0V, V _{DS} =-10V f=1.0MHz	-	4282	-	pF
Output capacitance	C _{OSS}		-	442	-	
Reverse transfer capacitance	C _{RSS}		-	403	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =-10V, V _{DD} =-20V, R _L =3Ω, I _D =20A, R _G =2.5Ω	-	14.2	-	ns
Turn-on Rise time	t _r		-	35.4	-	
Turn-off delay time	t _{D(OFF)}		-	361	-	
Turn-off Fall time	t _f		-	224	-	
Total gate charge	Q _g	V _{GS} =-4.5V, I _D =-2A V _{DS} =-10V	-	43.8	-	nC
Gate-source charge	Q _{gs}		-	5.8	-	
Gate-drain charge	Q _{gd}		-	10.5	-	

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient ^A	≤ 10s	R _{θJA}	20	°C/W
Maximum Junction-to-Ambient ^A	Steady-State		55	
Maximum Junction-to-Lead ^B	Steady-State	R _{θJC}	1.2	

A: The value of R_{θJA} is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

Typical Performance Characteristics

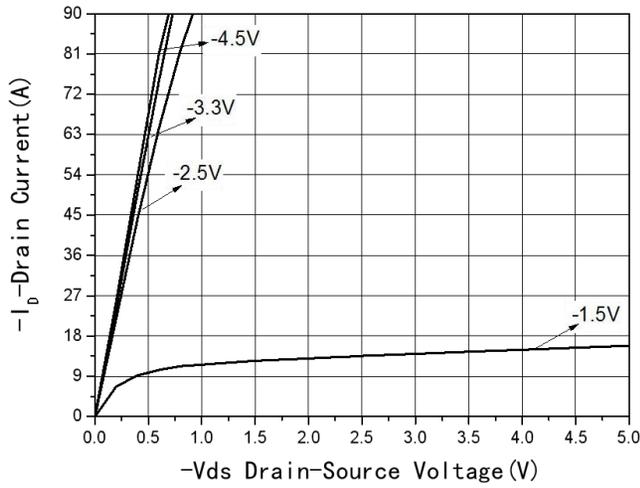


Fig1 Output Characteristics

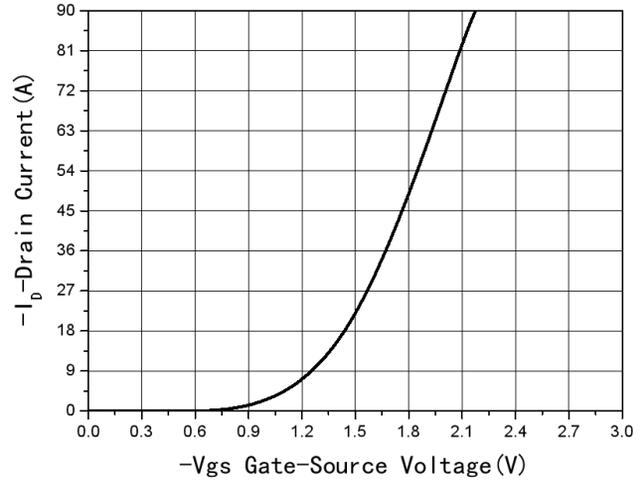


Fig2 Transfer Characteristics

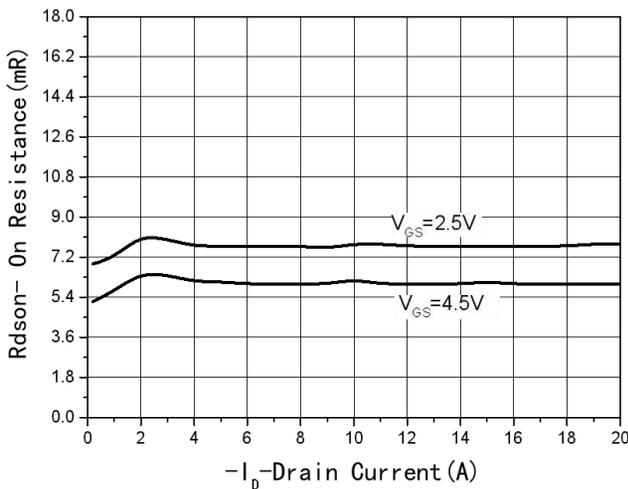


Fig3 $R_{DS(on)}$ -Drain current

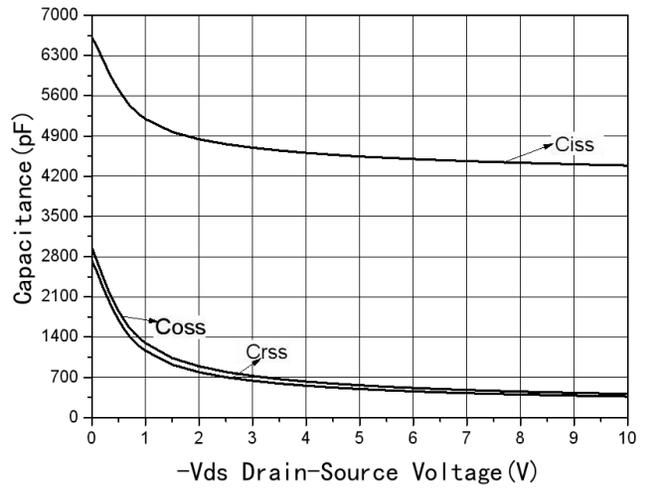


Fig4 Capacitance vs V_{DS}

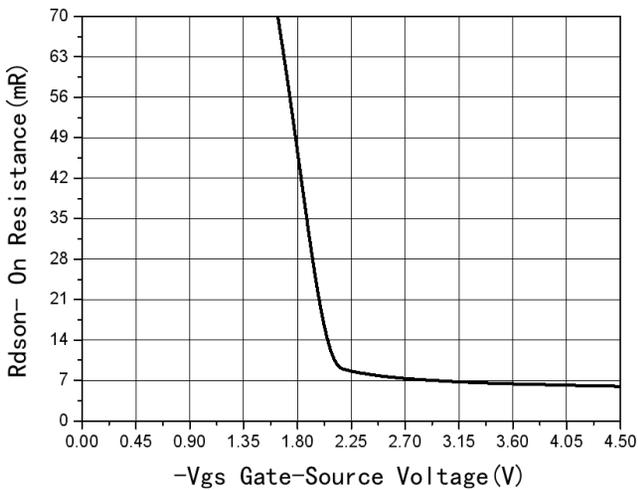


Fig5 $R_{DS(on)}$ -Gate Drain voltage

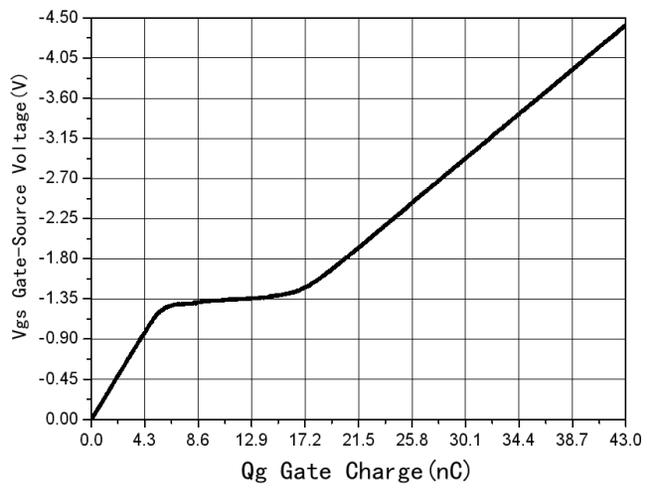
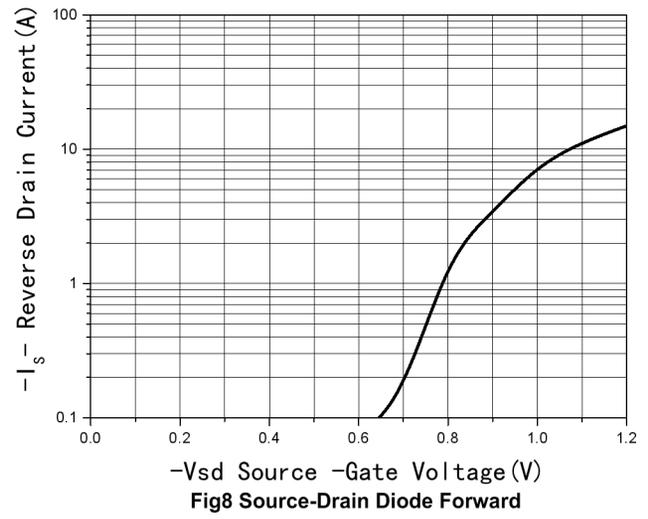
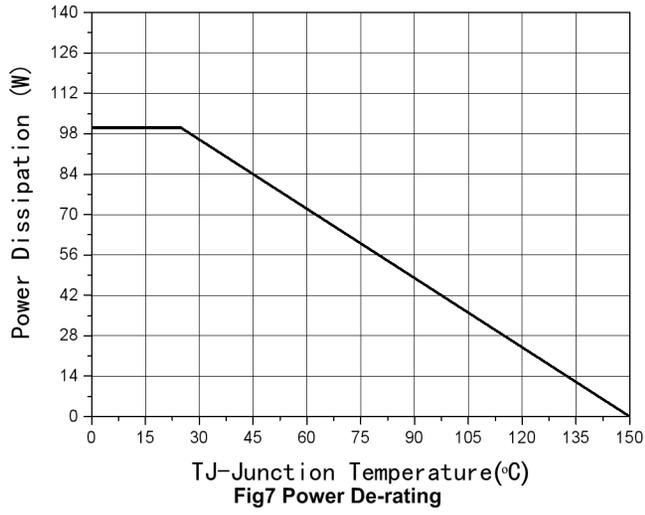
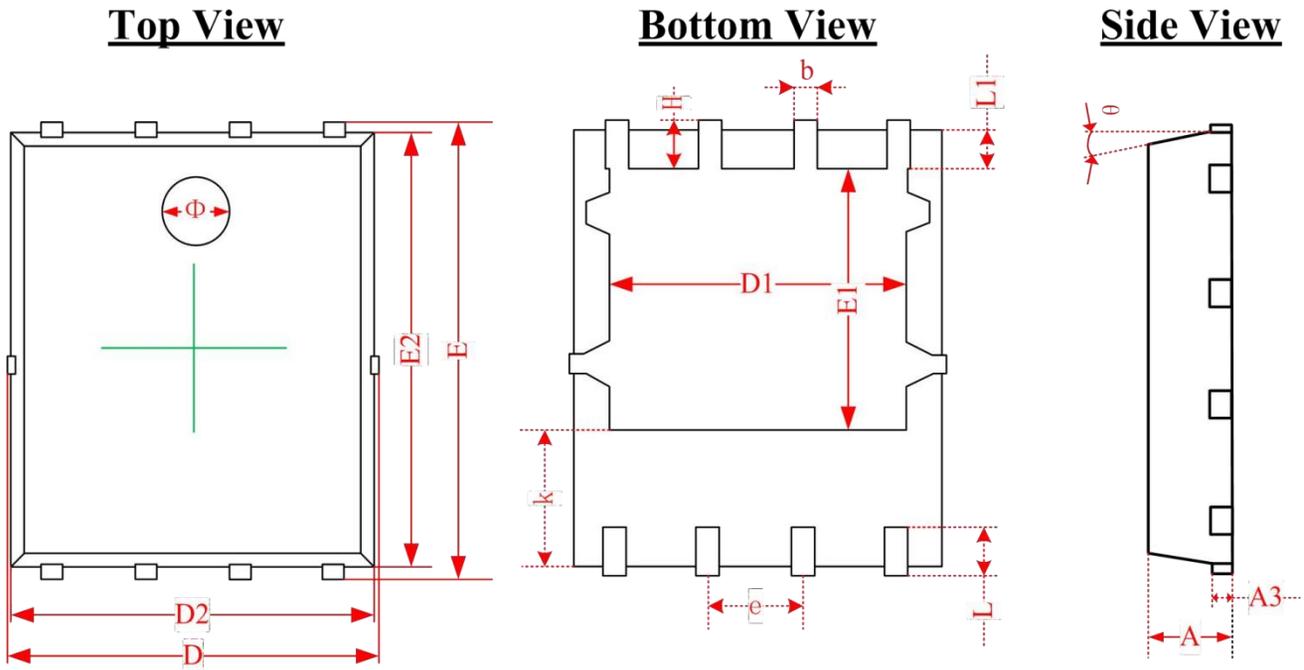


Fig6 Gate Charge



Package Information

- PDFN5*6-8L-A



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.870	0.900	0.930	0.034	0.035	0.036
A3	0.203REF.			0.008REF.		
D	4.944	5.020	5.096	0.195	0.198	0.201
E	5.974	6.050	6.126	0.235	0.238	0.241
D1	3.910	4.010	4.110	0.154	0.158	0.162
E1	3.375	3.475	3.575	0.133	0.137	0.141
D2	4.870	4.900	4.930	0.192	0.193	0.194
E2	5.720	5.750	5.780	0.226	0.227	0.228
k	1.190	1.290	1.390	0.047	0.051	0.055
b	0.350	0.380	0.410	0.014	0.015	0.016
e	1.270TYP.			0.050TYP.		
L	0.559	0.635	0.711	0.022	0.025	0.028
L1	0.424	0.500	0.576	0.017	0.020	0.023
H	0.574	0.650	0.726	0.023	0.026	0.029
θ	10°	11°	12°	10°	11°	12°
Φ	1.150	1.200	1.250	0.045	0.047	0.049